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(74) Agents: HARTS, Dean M., et al.; Office of Intellectual Property Counsel, Post Office Box 33427, Saint Paul, MN 55133-3427 (US).

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(71) Applicant (for all designated States except US): 3M INNOVATIVE PROPERTIES COMPANY [US/US]; 3M Center, Post Office Box 33427, Saint Paul, MN 55133-3427 (US).

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(72) Inventors; and

(75) Inventors/Applicants (for US only): TAKEUCHI, Shoji [JP/JP]; 16-8-304, Yabe 4-chome, Sagamihara, Kanagawa 229-0032 (JP). KAWATE, Kohichiro [JP/JP]; 8-13-12, Tamagawagakuen, Machida, Tokyo 194-0041 (JP). SAKAKIBARA, Makoto [JP/JP]; 128-163, Kawamachi, Hachioji, Tokyo 193-0321 (JP).

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(54) Title: HEAT CURABLE ADHESIVE COMPOSITION, ARTICLE, SEMICONDUCTOR APPARATUS AND METHOD

(57) Abstract: Provided are a heat curable adhesive composition and an adhesive article suited for dicing of a semiconductor and die-bonding of the diced semiconductor chip, and a semiconductor apparatus and a process for preparing a semiconductor apparatus using the adhesive composition and article. In one embodiment, the present invention provides a heat curable adhesive composition comprising a caprolactone-modified epoxy resin and a tack reducing component. Another embodiment of the present invention provides an adhesive article comprising a heat curable adhesive layer of a heat curable adhesive composition comprising a caprolactone-modified epoxy resin, a tack reducing component, and a backing layer carrying said adhesive layer on at least a portion of the backing layer.

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PCT/US 03/19712A. CLASSIFICATION OF SUBJECT MATTER
IPC 7 C09J163/00 H01L21/00 C09J11/00

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)
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Electronic data base consulted during the international search (name of data base and, where practical, search terms used)

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C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category °	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
Y	PATENT ABSTRACTS OF JAPAN vol. 2002, no. 09, 4 September 2002 (2002-09-04) & JP 2002 146319 A (THREE M INNOVATIVE PROPERTIES CO), 22 May 2002 (2002-05-22) cited in the application abstract ---	1-8
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Name and mailing address of the ISA

European Patent Office, P.B. 5818 Patentlaan 2
NL - 2280 HV Rijswijk
Tel. (+31-70) 340-2040, Tx. 31 651 epo nl,
Fax: (+31-70) 340-3016

Authorized officer

Marsitzky, D

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